



Material Content Data Sheet



Sales Product Name	TLE4905L			Issued		28. August 2013		
MA#	MA000504152							
Package	PG-SSO-3-2			Weight*		83.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.501	0.60	0.60	6006	6006
leadframe	non noble metal	chromium	7440-47-3	0.153	0.18		1835	
	non noble metal	titanium	7440-32-6	0.153	0.18		1835	
	noble metal	silver	7440-22-4	0.204	0.24		2447	
	non noble metal	tin	7440-31-5	0.306	0.37		3670	
	non noble metal	copper	7440-50-8	50.200	60.20	61.17	601882	611669
wire	noble metal	gold	7440-57-5	0.030	0.04	0.04	361	361
encapsulation	organic material	carbon black	1333-86-4	0.211	0.25		2531	
	plastics	brominated resin	-	0.264	0.32		3164	
	inorganic material	antimonytrioxide	1309-64-4	0.528	0.63		6328	
	plastics	epoxy resin	-	4.803	5.76		57583	
	inorganic material	silicondioxide	60676-86-0	20.583	24.68	31.64	246786	316392
leadfinish	non noble metal	tin	7440-31-5	4.889	5.86	5.86	58619	58619
plating	noble metal	silver	7440-22-4	0.284	0.34	0.34	3410	3410
glue	plastics	epoxy resin	-	0.059	0.07		709	
	noble metal	silver	7440-22-4	0.236	0.28	0.35	2834	3543
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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